Product Qualification Report

BGA7H1N6

Silicon Germanium Low Noise Amplifier for LTE

Description

This product qualification report describes the characteristics of the product with respect to quality and reliability.

The qualification sample selection was done on production lots which were manufactured and tested on standard production processes and meet the defined requirements.

The qualification test results of those products as outlined in this document are based on **JEDEC** for target applications and may reference existing qualification results of similar products. Such referencing is justified by the structural similarity of the products.

Qualification Assessment

Fully qualified according to **JEDEC** for **Industrial Applications** and assessed as PASS

For further information about comparable products, please contact the nearest Infineon Technologies office (www.infineon.com).

BGA7H1N6 **qualified 2014**
PG-TSNP-6-2
MSL: 1; 260 °C

Electrical Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
Electrical Parameter Assessment JESD86	ED	-40 °C, 25 °C, 85 °C		3 x 10	0 / 30	PASS
High Temperature Storage Life JESD22-A103	HTSL	T_a = 150 °C	1000 h	3 x 25	0 / 75	PASS
Electrostatic Discharge Human Body Model JS-001	ESD-HBM	Class 2 2000 V to < 4000 V		1 x 3	0 / 3	PASS
Electrostatic Discharge Charged Device Model JS-002	ESD-CDM	Class C3 ≥ 1000 V		1 x 3	0 / 3	PASS
Latch Up JESD78	LU	T_a = 85 °C $I_{trigger}$ = 150 mA		1 x 3	0 / 3	PASS

Environmental Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
Pre-conditioning JESD22-A113, J-STD020	PC	Soak acc. MSL 1, 3x reflow, 260 °C		3 x 50	0 / 150	PASS
Temperature Cycling JESD22-A104	TC*	-40 °C to 125 °C	1000 cycles	3 x 25	0 / 75	PASS
Temperature Humidity Bias JESD22-A101	THB*	T_a = 85 °C rh = 85 % V_{dd} = V_{dd_max}	96 h	3 x 25	0 / 75	PASS

Mechanical Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
Physical Dimensions JESD22-B100	PD			1 x 30	0 / 30	PASS
Solderability J-STD-002	SD			3 x 22	0 / 66	PASS

Notes:
* For SMD devices reliability stress tests performed after preconditioning test (PC) according to JESD22-A113

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Document reference

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